

Features

- DC - 2.5 GHz
- 40 Watts
- BeO Ceramic
- Welded Silver Leads
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

Resistive Element:	Thick film
Substrate:	Beryllium oxide ceramic
Cover:	Alumina ceramic
Lead(s):	99.99% pure silver (.005" thk)

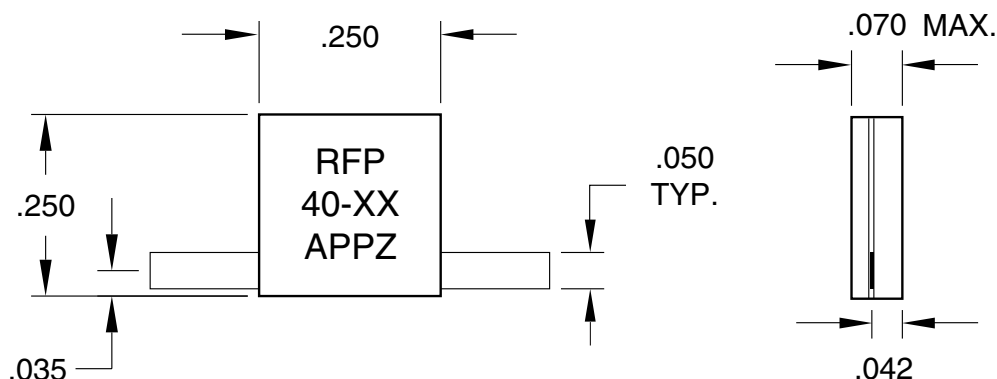
Electrical Specifications

Attenuation Value:	1, 2, 3, 4, 5, 6, 9, 10, 20 or 30 dB
Frequency Range:	DC - 2.5 GHz
Power:	40 Watts

Notes: Tolerance is ± 0.10 , unless otherwise specified. Operating temperature is -55°C to $+150^{\circ}\text{C}$ (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. Lead length 0.15" minimum.

Specifications subject to change without notice.

Outline Drawing



Note: XX denotes attenuation value.

VER.12/4/01

Model RFP-40-XXAPPZ

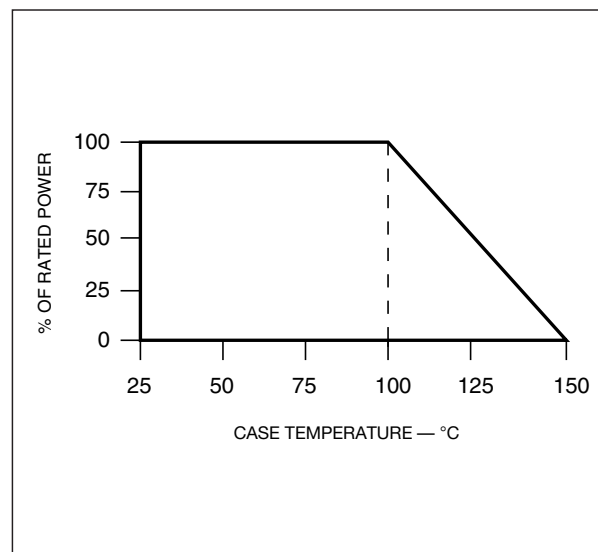
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RF Power

Specifications

PART NUMBER	ATTENUATION (dB)	TOL. (+/-dB)	POWER (WATTS)	VSWR	FREQ. (GHz)
RFP-40-1APPZ	1	0.50	40	1.20:1	2.5
RFP-40-2APPZ	2	0.50	40	1.20:1	2.5
RFP-40-3APPZ	3	0.50	40	1.20:1	2.5
RFP-40-4APPZ	4	0.50	40	1.20:1	2.5
RFP-40-5APPZ	5	0.50	40	1.20:1	2.5
RFP-40-6APPZ	6	0.50	40	1.20:1	2.5
RFP-40-9APPZ	9	0.50	40	1.25:1	2.5
RFP-40-10APPZ	10	0.50	40	1.25:1	2.5
RFP-40-20APPZ	20	1.00	40	1.20:1	2.5
RFP-40-30APPZ	30	1.50	40	1.20:1	2.0

Power Derating



Suggested Mounting Procedures

.025 MIN.
(2 PLACES)

BOARD LOWER THAN LEAD. BOARD EVEN WITH LEAD.

SUGGESTED STRESS RELIEF METHODS

SCALE: ~~~~~

BOARD LOWER THAN LEAD. BOARD HIGHER THAN LEAD.

NOT RECOMMENDED APPLICATION

SCALE: ~~~~~

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Position device on mounting surface and solder in place using an indalloy type or an SN63 type solder.
3. Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).